

Appl. No. : 09/960,236
Filed : September 20, 2001

AMENDMENTS TO THE SPECIFICATION

On page 2, please replace the third full paragraph with the following replacement paragraph:

Further, U.S. Patent Application No. 09/511,278 entitled "Pad Designs and Structures for a Versatile Materials Processing Apparatus" filed February 23, 2000, and U.S. Patent Application No. 09/621,969 entitled "Pad Designs and Structures With improved Fluid Distribution" filed July 21, 2000, and both assigned to the same assignee as the present invention, describe, among other aspects, pad designs that assist in providing surface with a uniform material overburden. In particular, Fig. 12 of U.S. Patent Application No. 09/511,278, ~~illustrated as Fig. 15 herein,~~ shows channels in the form of slits 120 and circular openings 121.

On page 11, please replace the third full paragraph with the following replacement paragraph:

In this embodiment, the holes 202 within the channel regions 215, 216 are formed with a shape that the inner and outer walls correspond to the arc at a given radius from the center of the mask ~~late plate~~ 200, and are progressively smaller in size as they get closer to the center of the mask, and are distributed on opposite sides from the center of the mask in a staggered manner (hole 202a lines up with space 203a as shown) to ensure that the entire wafer 108 will receive a uniform application of electrolyte. As shown in Figures 8A-8D, the top surface 222 of the raised regions 214 may ~~have be~~ designed to have a plurality of very small circular, rectangular, bump, round, or triangular shape features. While the top surface 222 may appear smooth ~~is looked at as seen~~ from a distance, close inspection will show that the top surface is made up of many of these small shaped features. Such features may comprise abrasives on them, and can also contain abrasives within them, so as the top surface 222 becomes worn, abrasives still exist which can contact the wafer. Alternatively, the top surfaces 222 may be shaped as rectangular, bump, round or triangular. These shapes improve the sweeping action on the wafer surface.